SURFACE MOUNT SILICON
TRIPLE ISOLATED
HIGH VOLTAGE
SCHOTTKY DIODE



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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMKD6263 contains three (3) galvanically isolated, high voltage Silicon Schottky diodes, epoxy molded in a SOT-363 surface mount package. This ULTRAmini™ device has been designed for fast switching applications requiring a low forward voltage drop.

MARKING CODE: K63



FEATURES:

- Meets Galvanic Isolation Requirements of IEEE 1394
- High Voltage (70V)

- Requires less board space than 3 individual diodes
- Low Forward Voltage

MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V_{RRM}	70	V
Continuous Forward Current	Ι _F	15	mA
Peak Forward Surge Current, tp=1.0s	^I FSM	50	mA
Power Dissipation	P_{D}	250	mW
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	500	°C/W

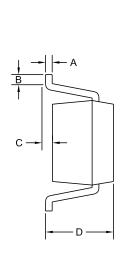
ELECTRICAL CHARACTERISTICS PER DIODE: (T_A=25°C unless otherwise noted)

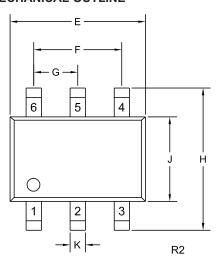
SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
I_R	V _R =50V		10	200	nA
BV_R	I _R =10μA	70			V
V_{F}	I _F =1.0mA		395	410	mV
C_{J}	$V_R=0$, f=1.0MHz			2.0	pF
t _{rr}	$I_R=I_F=10$ mA, $I_{rr}=1.0$ mA, $R_L=100$ Ω			5.0	ns

SURFACE MOUNT SILICON TRIPLE ISOLATED HIGH VOLTAGE SCHOTTKY DIODE

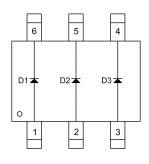


SOT-363 CASE - MECHANICAL OUTLINE





PIN CONFIGURATION



DIMENSIONS						
	INCHES		MILLIMETERS			
SYMBOL	MIN	MAX	MIN	MAX		
Α	0.004	0.010	0.10	0.25		
В	0.005	-	0.12	-		
С	0.000	0.004	0.00	0.10		
D	0.031	0.043	0.80	1.10		
E	0.071	0.087	1.80	2.20		
F	0.051		1.30			
G	0.026		0.65			
Н	0.075	0.091	1.90	2.30		
J	0.043	0.055	1.10	1.40		
K	0.006	0.012	0.15	0.30		

SOT-363 (REV: R2)

LEAD CODE:

- 1) Anode D1
- 2) Anode D2
- 3) Anode D3
- 4) Cathode D3
- 5) Cathode D2
- 6) Cathode D1

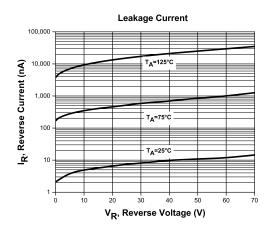
MARKING CODE: K63

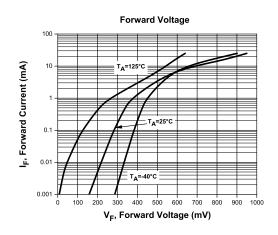
R5 (11-December 2015)

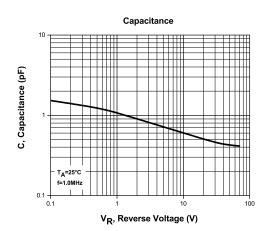
SURFACE MOUNT SILICON TRIPLE ISOLATED HIGH VOLTAGE SCHOTTKY DIODE

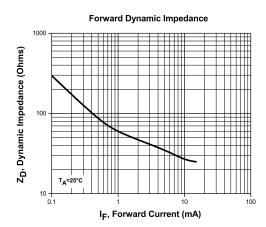


TYPICAL ELECTRICAL CHARACTERISTICS





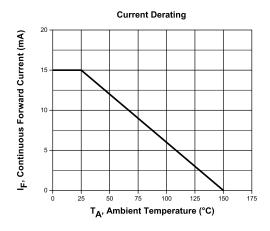


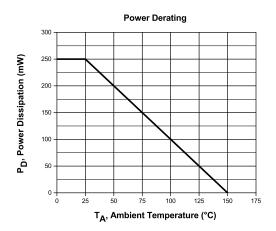






TYPICAL ELECTRICAL CHARACTERISTICS





OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- · Package details
- Application notes
- · Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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